

1200mW Audio Power Amp with Shutdown

Features

- Operating voltage: 2.2V to 5.5V
- · High signal-to-noise ratio
- Low distortion
- · Large output voltage swing
- Low power consumption
- Output power 1200mW at 10% THD+N into 8Ω (V_{DD} =5V)
- · Wide temperature operating range
- Low power-on and chip enable or disable POP noise.
- · Low standby current
- Power off control
- · Direct drive speaker
- 8-pin DIP/SOP package

Applications

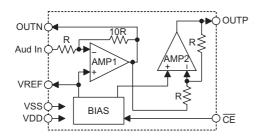
 Applied for HT36 series, HT86 series and other Holtek products

General Description

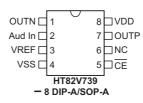
HT82V739 is an integrated class AB mono speaker driver contained in a 8-pin DIP/SOP package. The HT82V739 is capable of delivering 1200mW output power to an 8Ω load with less than 10% (THD+N) from a

5V power supply. The very low standby current in shutdown mode contributes to the reduction of power consumption of battery-powered equipments.

Block Diagram



Pin Assignment



Pin Description

Pin No.	Pin Name	I/O	Description	
1	OUTN	0	Negative output	
2	Aud In	I	Audio input	
3	VREF	0	Speaker non-inverting input voltage reference	
4	VSS	_	Negative power supply, ground	
5	CE	ı	Chip enable, low active	
6	NC	_	Not connected	
7	OUTP	0	Positive output	
8	VDD	_	Positive power supply	



Absolute Maximum Ratings

Supply VoltageV _{SS} -0.3V to V _{SS} +6.0V	Storage Temperature50°C to 125°C
Input VoltageV _{SS} -0.3V to V _{DD} +0.3V	Operating Temperature40°C to 85°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Electrical Characteristics

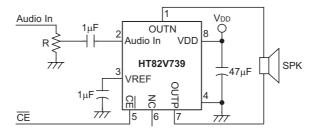
V_{SS}=0V, Ta=25°C

Symbol	bol Parameter		Test Conditions			Tves	May	Unit
Symbol			V _{DD} Conditions			Тур.	Max.	Unit
D.C. Cha	racteristics							
V_{DD}	Supply Voltage	_	_		2.2	5.0	5.5	V
. Quiescent Power Su	Quiescent Power Supply	3V	\/ =0\/ No load		_	2.2	4.0	mA
I _{DD}	Current	5V	V _{IN} =0V _{P-P} , No load		_	3.5	6.0	mA
I _{SD}	Shutdown Power Supply Current	5V	V _{IN} =0V _{P-P} , CE=V _{DD} , No	load	_	_	1	μА
V _{IH}	Input High Voltage for CE	_	_		0.7V _{DD}		V _{DD}	V
V _{IL}	Input Low Voltage for CE	_	_		0		0.3V _{DD}	V
			(THD+N)/S≤1%, V _{IN} =1kHz sinewave	$R_L=4\Omega$	_	330		mW
				R _L =8Ω	_	300		
		0) (VIII TIM IZ SITIEWAYS	R _L =16Ω	_	240	_	
		3V		$R_L=4\Omega$	_	450		
P ₀	Output Power		(THD+N)/S≤10%, V _{IN} =1kHz sinewave	R _L =8Ω	_	400		
				R _L =16Ω	_	280		
			(THD+N)/S≤1%, V _{IN} =1kHz sinewave	$R_L=4\Omega$	_	1150	_	- mW
		5V		R _L =8Ω	_	950		
				R _L =16Ω	_	650		
			(THD+N)/S≤10%, V _{IN} =1kHz sinewave	$R_L=4\Omega$	_	1400	_	
				R _L =8Ω	_	1200	_	
			THE THE STATE OF T	R _L =16Ω	_	800	_	
A.C. Cha	racteristics							
tou	Enable Time		V _{IN} =1kHz sinewave, No load		_	145		μS
t _{ON}						105		μS
(THD+N) /S				$R_L=4\Omega$	_	0.3		%
	Total Harmonic Distortion Plus Noise-to-signal Ratio	5V	Power Output=500mW, V _{IN} =1kHz sinewave	R _L =8Ω	_	0.18	_	%
	Noise-tu-signal Ratio		TIN THE SHICWAY	R _L =16Ω		0.13		%
				$R_L=4\Omega$	_	66		dB
S/N	Signal to Noise Ratio		V _{IN} =1Vrms 1kHz sinewave	R _L =8Ω		70	_	dB
				R _L =16Ω	_	72		dB

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Application Circuits



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Package Information

8-pin DIP (300mil) Outline Dimensions





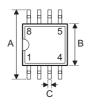


Complete	Dimensions in mil				
Symbol	Min.	Nom.	Max.		
А	355	_	375		
В	240	_	260		
С	125	_	135		
D	125	_	145		
E	16	_	20		
F	50	_	70		
G	_	100	_		
Н	295	_	315		
ļ	335	_	375		
α	0°	_	15°		

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8-pin SOP (150mil) Outline Dimensions





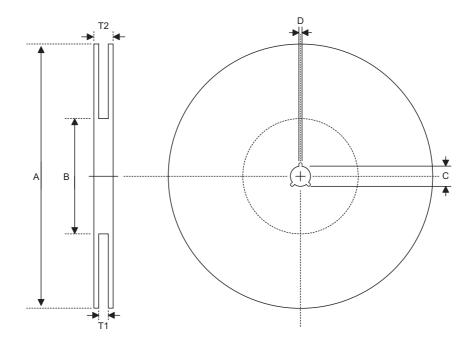


Symbol	Dimensions in mil				
Symbol	Min.	Nom.	Max.		
Α	228	_	244		
В	149	_	157		
С	14	_	20		
C'	189	_	197		
D	53	_	69		
E	_	50	_		
F	4	_	10		
G	22	_	28		
Н	4	_	12		
α	0°	_	10°		



Product Tape and Reel Specifications

Reel Dimensions

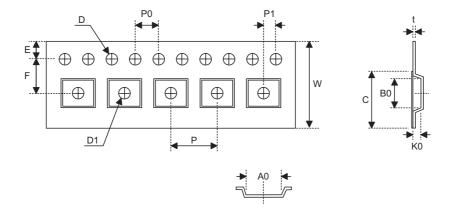


SOP 8N

Symbol	Description	Dimensions in mm
А	Reel Outer Diameter	330±1.0
В	Reel Inner Diameter	62±1.5
С	Spindle Hole Diameter	13.0+0.5 -0.2
D	Key Slit Width	2.0±0.15
T1	Space Between Flange	12.8+0.3 -0.2
T2	Reel Thickness	18.2±0.2



Carrier Tape Dimensions



SOP 8N

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0+0.3 -0.1
Р	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.1
D	Perforation Diameter	1.55±0.1
D1	Cavity Hole Diameter	1.5+0.25
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	6.4±0.1
В0	Cavity Width	5.20±0.1
K0	Cavity Depth	2.1±0.1
t	Carrier Tape Thickness	0.3±0.05
С	Cover Tape Width	9.3



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